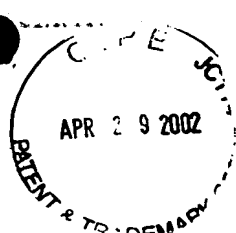


WMP-EUP-008



1700
1752
COPY OF PAPERS
ORIGINALLY FILED
#4/A
6/5/02

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

By: 

Date: Apr. 18, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Gottfried Ferber et al.
Applic. No. : 10/056,770
Filed : January 24, 2002
Title : Semiconductor Module and Method for
Fabricating the Semiconductor Module

P R E L I M I N A R Y A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

S i r :

Preliminary to examination, kindly amend the above-identified
application as follows:

In the Claims:

RECEIVED
MAY 06 2002
TC 1700

Sub B.1
A1
Claim 1 (amended). A semiconductor module, comprising:

a substrate body having an insulating ceramic layer with a top
side, and a metal layer fixedly joined to said top side of
said insulating ceramic layer;